

## PATENT ASSIGNMENT COVER SHEET

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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
AI-TEE ANG	10/11/2017
SHING-CHAO CHEN	10/11/2017
CHING-HUA HSIEH	10/11/2017
CHIH-WEI LIN	10/11/2017
CHING-YAO LIN	10/11/2017
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<b>City:</b>	HSINCHU
<b>State/Country:</b>	TAIWAN
<b>Postal Code:</b>	300-78
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	15715132
<b>CORRESPONDENCE DATA</b>	
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<b>NAME OF SUBMITTER:</b>	BELINDA LEE
<b>SIGNATURE:</b>	/Belinda Lee/
<b>DATE SIGNED:</b>	11/01/2017
<b>Total Attachments: 3</b>	
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**DECLARATION AND ASSIGNMENT  
FOR UTILITY OR DESIGN PATENT APPLICATION**

☐ Declaration Submitted With Initial Filing

OR

☒ Declaration Submitted After Initial Filing (surcharge 37 CFR 1.16(f) required)

(Title of the Invention)

**INTEGRATED FAN-OUT PACKAGE AND MANUFACTURING METHOD  
THEREOF**

As a below named inventor (hereinafter designated as the undersigned), I hereby declare  
that:

This declaration is directed to:

☐ The attached application,

OR

☒ United States Application Number or PCT International application number 15/715,132

Filed on 2017/9/25

The above-identified application was made or authorized to be made by me.

I believe I am the original inventor or an original joint inventor of a claimed invention in the  
application.

The undersigned hereby acknowledge that any willful false statement made in this  
declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five  
(5) years, or both.

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**DECLARATION AND ASSIGNMENT  
FOR UTILITY OR DESIGN PATENT APPLICATION**

WHEREAS, the undersigned has invented certain new and useful improvements described in the application identified.

WHEREAS 1. Taiwan Semiconductor Manufacturing Co., Ltd.  
of No.8, Li-Hsin Rd. 6, Hsinchu Science Park, Hsinchu, Taiwan 300-78,  
R.O.C.

hereinafter referred to as ASSIGNEE, is desirous of acquiring the undersigned's interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same:

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by the undersigned, the undersigned has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said rights, title and interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said the undersigned had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

The undersigned further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee Lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

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**DECLARATION AND ASSIGNMENT  
FOR UTILITY OR DESIGN PATENT APPLICATION**

Signature: Ai-Tee Ang Date: 2017/10/11

Legal Name of Sole or First Inventor: Ai-Tee Ang

Residence: Hsinchu City, Taiwan

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Signature: Shing-Chao Chen Date: 2017/10/11

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Residence: Hsinchu County, Taiwan

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Signature: Ching-Hua Hsieh Date: 2017/10/11

Legal Name of Additional Joint Inventor, if any: Ching-Hua Hsieh

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Signature: Chih-Wei Lin Date: 2017/10/11

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Signature: Ching-Yao Lin Date: 2017/10/11

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